Quality

1) C. M. Tan and K. T. Lau. "Automated wafer defect map generation for process yield improvement," in Int. Symp. on Integrated Circuits, Singapore, 2011.

2) C. M. Tan. "Identifying key parameters for risk based inspections (RBI) and failure mode effect analysis (FMEA) (invited)," presented at Int. Quality and Process control Conf., Bangkok, Jan. 2004.

3) T. K. Neo and C. M. Tan. "QFD implementation in a discrete semiconductor industry," in IEEE Annual Reliability and Maintainability Symp., 2002, pp. 484-489.

4) C. M. Tan and G. Zhang. "A new quality control parameter in wafer fabrication for wire bonding integrity," in SPIE on Microelectronic Yield, Reliability and Advanced Packaging, 2000.

5) T. K. Neo and C. M. Tan. "Integrating device modeling in QFD implementation for power electronics applications," in IEEE Canadian Conf. on Electrical and Computing Engineering, 2000, pp. 1187-1191.

6) C. M. Tan. "Computerization of quality control in

electronics components industry," in National Quality Management Conf., 1995.